

PRESS RELEASE

MacDermid Alpha Releases Systek ETS 1200 Pattern Plating Metallization for Embedded Trace Substrates

(Waterbury, CT USA) – August 6th, 2020 – MacDermid Alpha Electronics Solutions, a global leader in specialty materials for electronics, announces the release of Systek ETS 1200, the latest addition to the Systek family of IC Substrate manufacturing solutions.

Systek ETS 1200 is an advanced DC acid copper pattern plating process specifically formulated to plate fine lines and pads in embedded trace substrates. With the dimensions utilized in panel-level packaging growing ever finer and more electrically demanding, embedded trace technology provides the tight tolerances required to route the circuitry on the organic substrate. Systek ETS 1200 excels at plating the difficult to achieve trace profile tolerances and coplanarity requirements of the die interface outerlayer of the IC substrate. The process is production-proven with dimensions as fine as 7/7 µm lines and spaces and has capability to accommodate further density increases should substrate designers require them. Systek ETS 1200 plates traces with sharp cornered square trace profiles that are encased in build-up film for superior electrical isolation with very low impedance. Copper deposits plated with the Systek ETS 1200 bath exhibit very low internal stress and exceed IPC Class III standards for tensile strength and elongation, creating a durable interconnection with no warpage. Chemical process control is achieved with simple CVS analysis of a 3-component system, ensuring quality and ease of use.

MacDermid Enthone's Systek UVF 100 process for 2 in 1 RDL plating can be combined with the Systek ETS 1200 embedded trace technology, to create extremely high-density coreless buildup layers for panel-level packaging.

"Systek ETS 1200 has the ability to create some of the tightest circuit routing we have ever seen on organic substrates. We are excited to offer this embedded trace plating technology as part of our broad range of metallization solutions for panel-level packaging. Our customers are even more excited to see how it can impact their bottom-line profitability and available design capabilities." – Rich Bellemare, Director of Electrolytic Metallization, Circuitry Solutions.

For more information on Systek ETS 1200, please visit MacDermidAlpha.com

About MacDermid Alpha Electronics Solutions

Through the innovation of specialty chemicals and materials under our Alpha, Compugraphics, Kester, and MacDermid Enthone brands, MacDermid Alpha Electronics Solutions provides solutions that power electronics interconnection. We serve all global regions and every step of device manufacturing within each segment of the electronics supply chain. The experts in our Semiconductor Solutions, Circuitry Solutions, and Assembly Solutions divisions collaborate in design, implementation, and technical service to ensure success for our partner clients. Our solutions enable our customers' manufacture of extraordinary electronic devices at high productivity and reduced cycle time. Find out more at MacDermidAlpha.com.

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